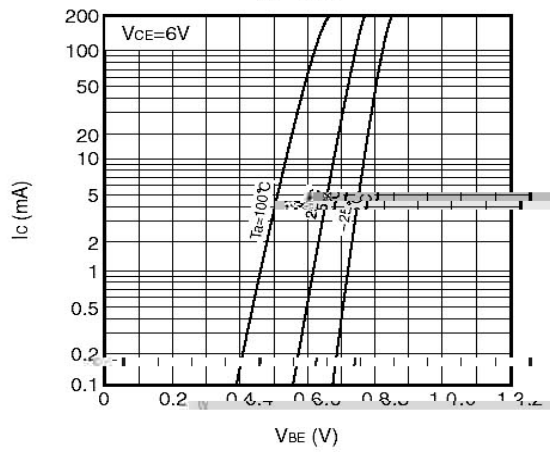
& 1VRW056 ṂṂ Ł QSQ ÆṀ ч s ǁ ˥ Silicon NPN 1 3NPN 25 Tw[S2stor in1 Tf411.057103 Tc0.0025 Tw[DA)23c

v ̈Ǫ Parameter	ɬ N Symbol	̈Ǫ Ö Rating	D Ɉ Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	50	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current	I_C	0.5	A
Collector Power Dissipation	P_C	0.3	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55˙ 150	

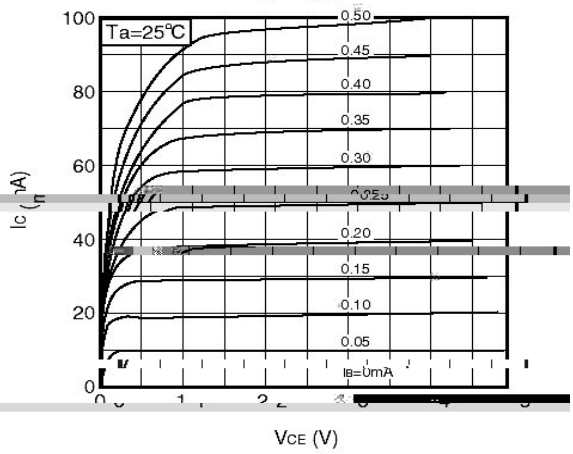
v ̈Ǫ Parameter	ɬ N Symbol	⊥ ;ˇ Ţ Test Conditions	ɷ ṇ Ö Min	Ɛ ʒ Ö Typ	ɷ ʑ Ö Max	D Ɉ Unit
Collector-Base Breakdown voltage	V_{CBO}	I_C=100 A I_E=0	50			V
Collector-Emitter Breakdown V						

/ Electrical Characteristic Curve

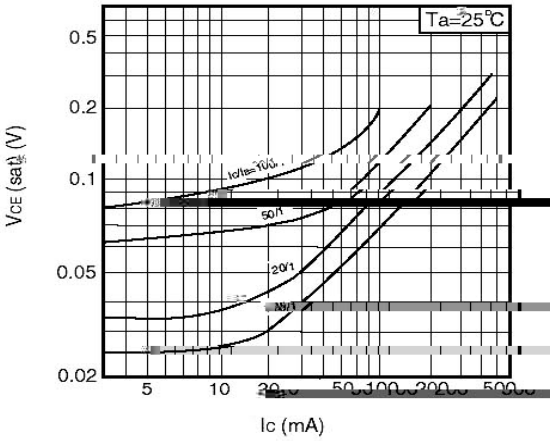
Ic — VBE



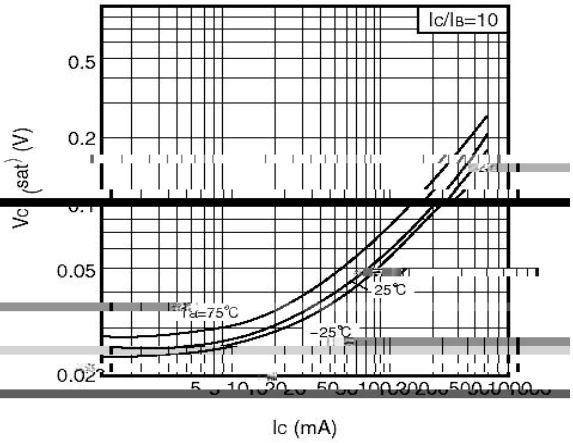
Ic — VCE



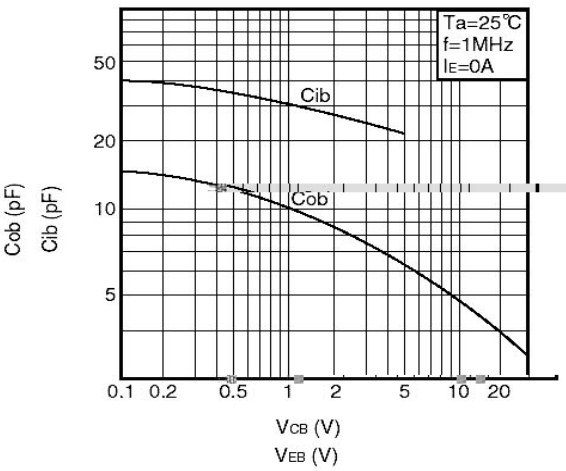
VCE (sat) — Ic



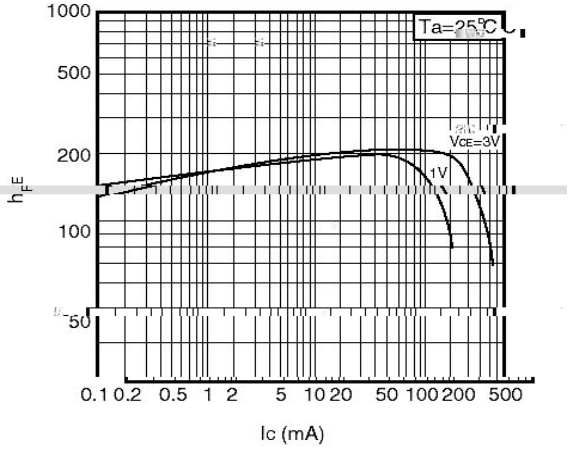
VCE (sat) — Ic



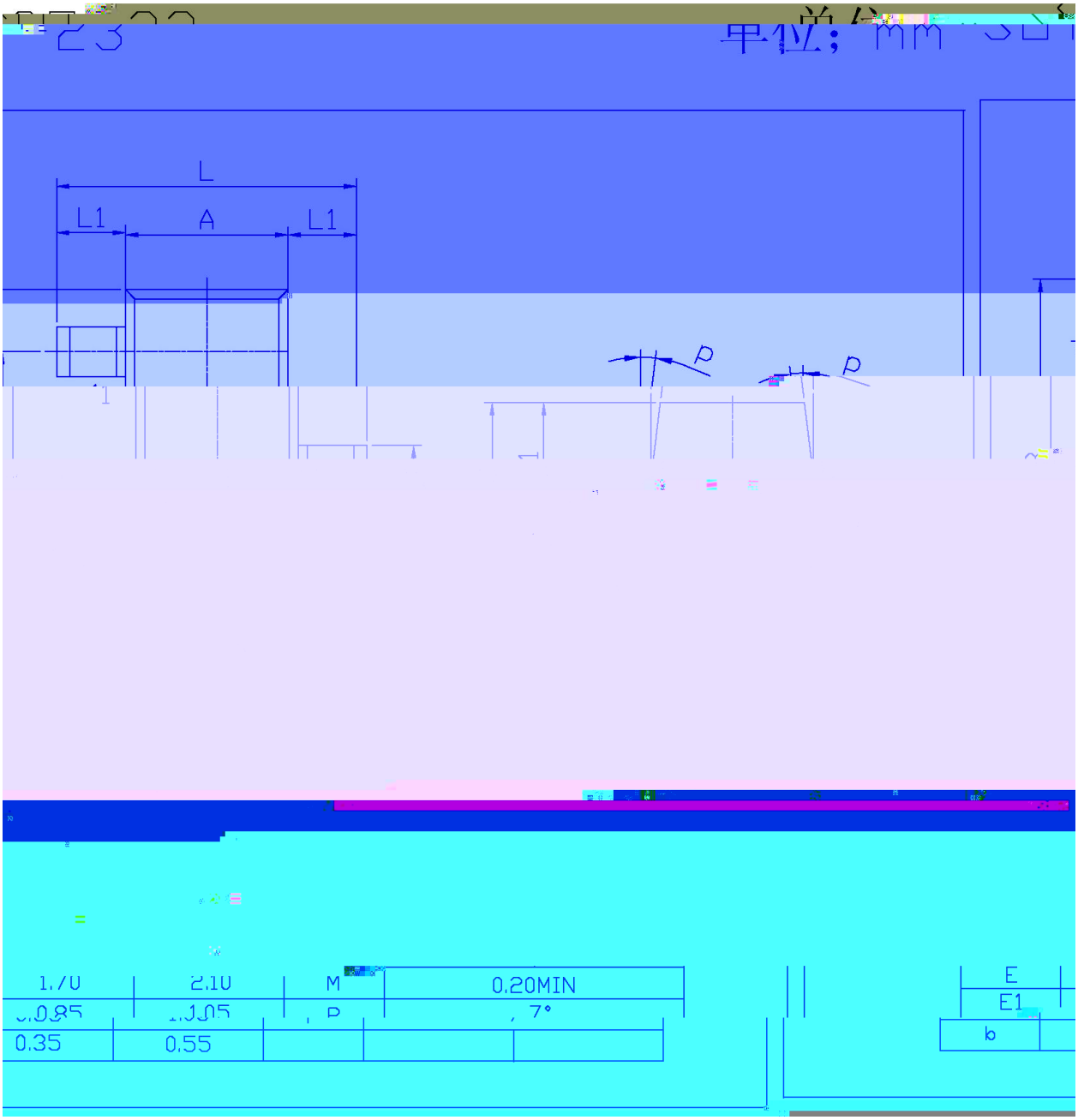
Cob — VCB
Cib — VEB



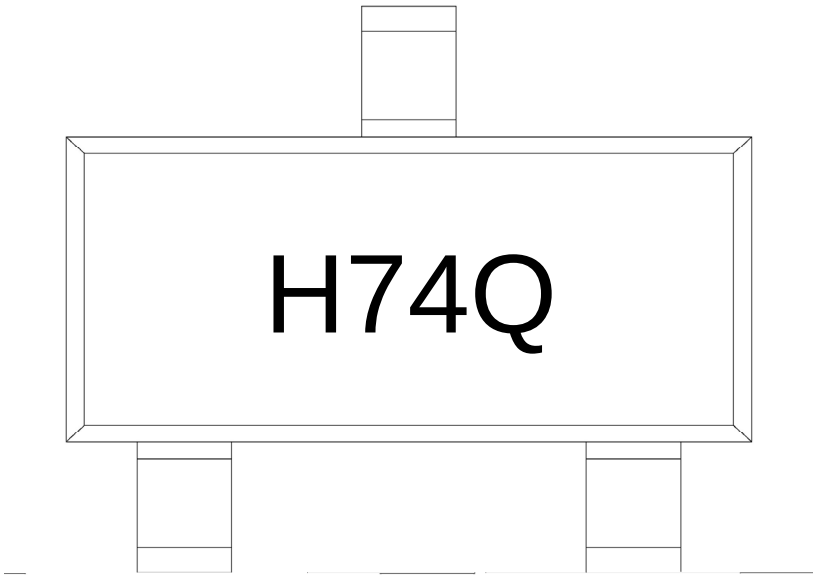
hFE — Ic



/ Package Dimensions



/ Marking Instructions



ب ˝ χ

K χ ѭ ʒ ᴵ Ɱ

:7 χ ѭ ʒ ᴺ Ɱ

T χ ѭ k_{IH} ᶠ ѬƱ

Note:

H: Company Code

74: Product Type Code

Q: h_{FE} Classifications Symbol Code

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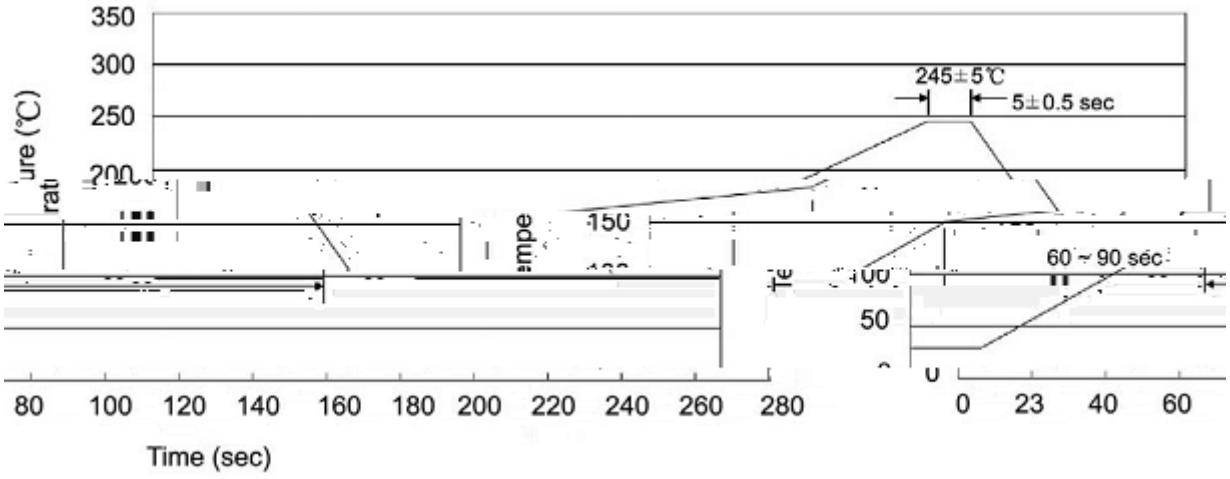
( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ

1 ℓ ♬ □ ỷ 25 Ḱ 150 ɫ ı `H ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 245 ° 5 ɫ ı `H ڑ ˋY ⺈ ⺮ 5 ° 0.5sec;

3 ì ˙ ⺈ ˛ ɔ ھ ỷ ⺮ 2 Ḱ 10 ɫ /sec.

Note:

1.Preheating:25~150 ɫ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɫ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɫ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɫ `H ڑ χ 10 ° 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

ɔ` γ ⊢ / REEL

Units Dimension (unit mm